

DSC7Q01

Silicon NPN epitaxial planar type darlington

For low frequency amplification
Darlington connection

■ Features

- High forward current transfer ratio h_{FE} with excellent linearity
- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 5K

■ Packaging

DSC7Q01×0L Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	100	V
Collector-emitter voltage (Base open)	V_{CEO}	80	V
Emitter-base voltage (Collector open)	V_{EBO}	5	V
Collector current	I_C	1	A
Peak collector current	I_{CP}	1.5	A
Collector power dissipation *1	P_C	1	W
Junction temperature	T_j	150	$^\circ\text{C}$
Operating ambient temperature	T_{opr}	-40 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

Absolute maximum rating without heat sink for P_C is 0.5 W

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 100 \mu\text{A}, I_E = 0$	100			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	80			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 100 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 25 \text{ V}, I_E = 0$			0.1	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 4 \text{ V}, I_C = 0$			0.1	μA
Forward current transfer ratio *1, 2	h_{FE}	$V_{CE} = 10 \text{ V}, I_C = 1 \text{ A}$	4000		40000	—
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = 1 \text{ A}, I_B = 1 \text{ mA}$			1.8	V
Base-emitter saturation voltage *1	$V_{BE(sat)}$	$I_C = 1 \text{ A}, I_B = 1 \text{ mA}$			2.2	V

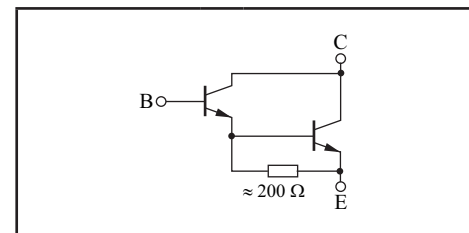
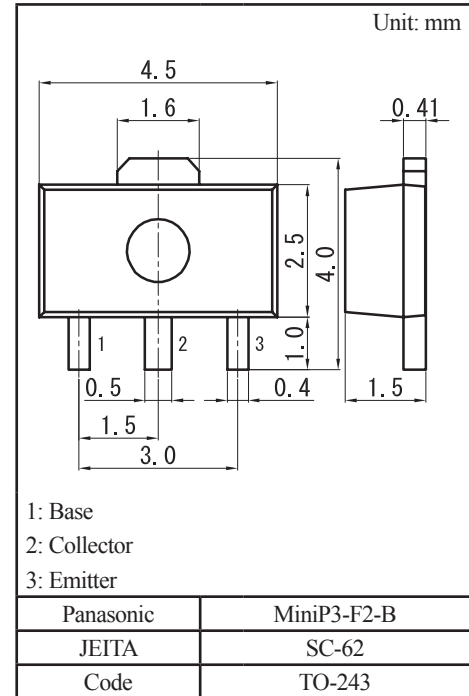
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

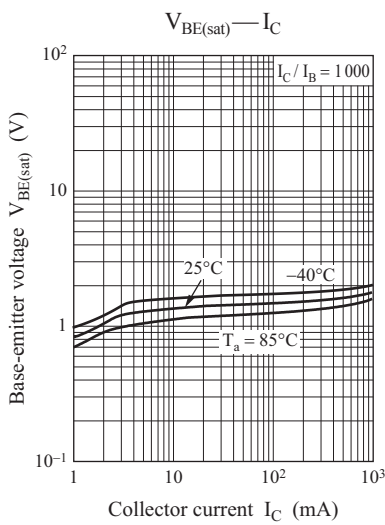
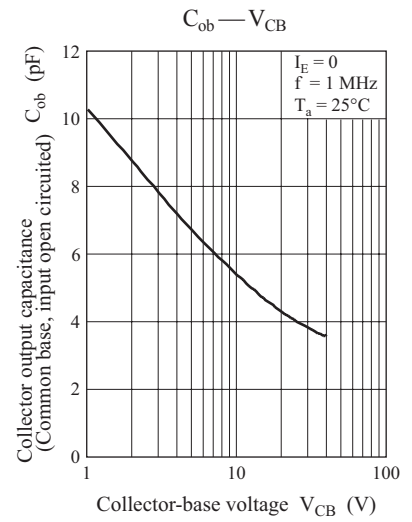
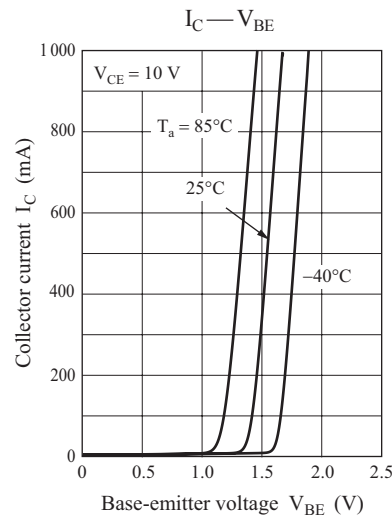
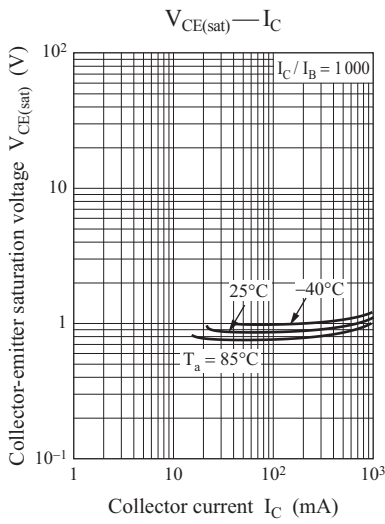
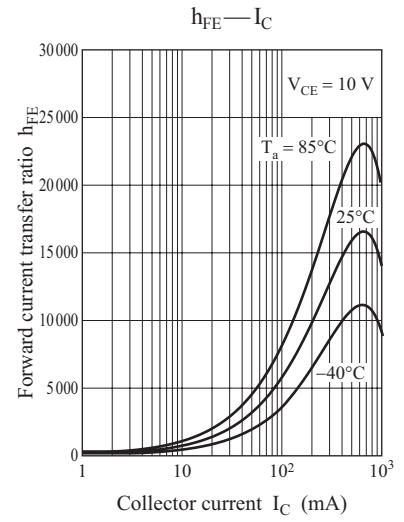
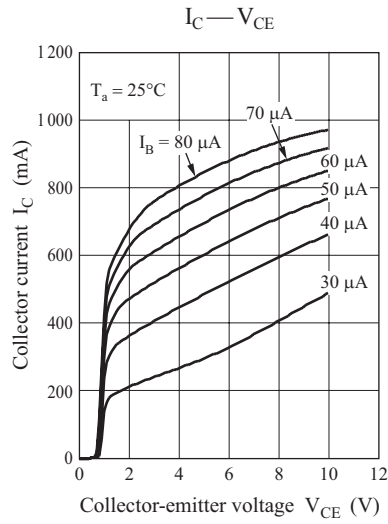
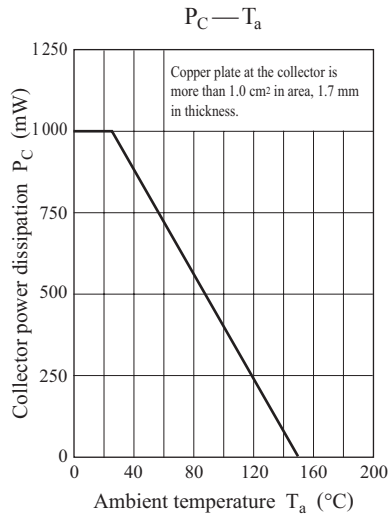
2. *1: Pulse measurement

*2: Rank classification

Code	Q	R	S	0
Rank	Q	R	S	No-rank
h_{FE}	4000 to 10000	8000 to 20000	16000 to 40000	4000 to 40000
Marking Symbol	5KQ	5KR	5KS	5K

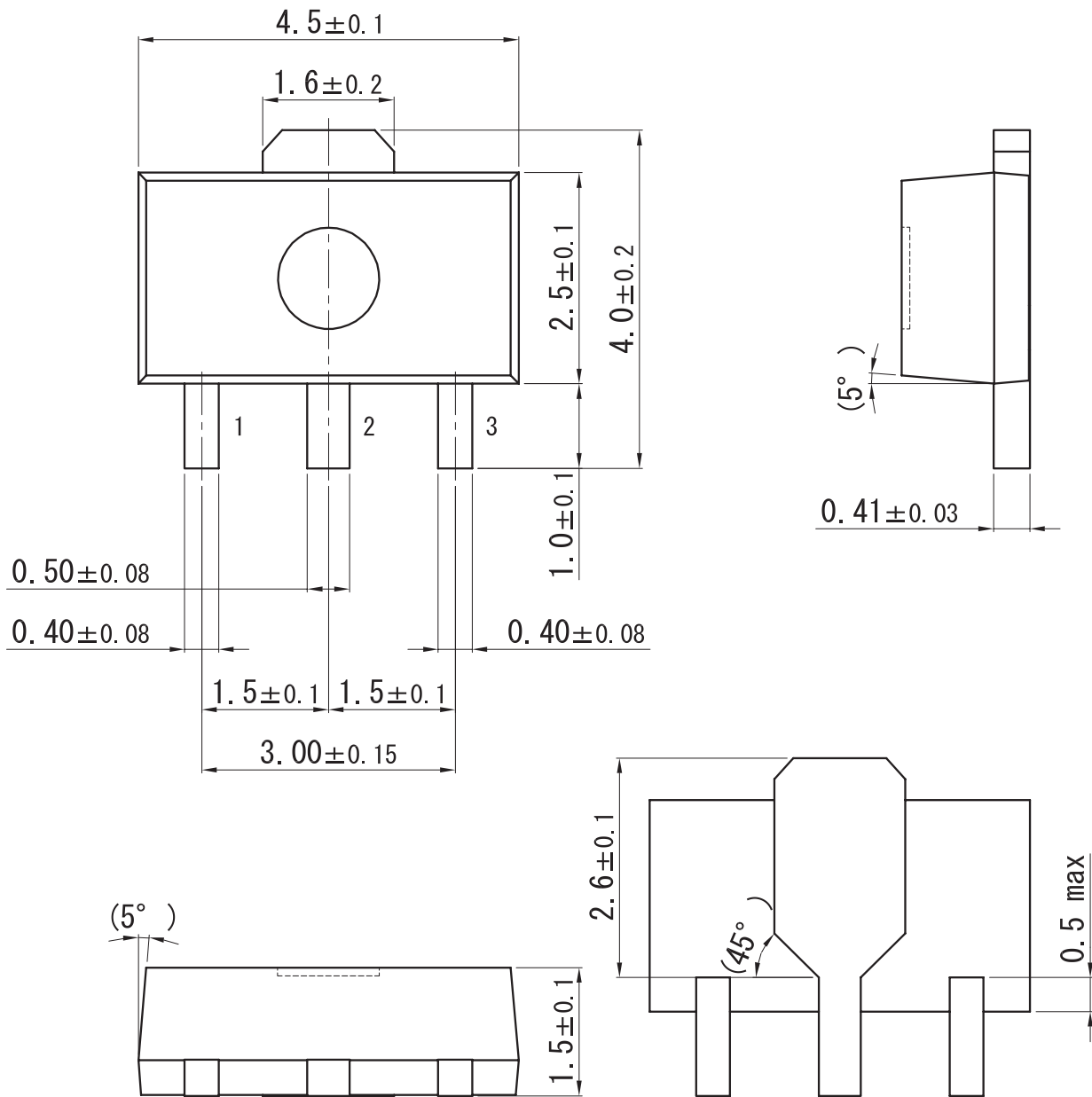
Product of no-rank is not classified and have no marking symbol for rank.



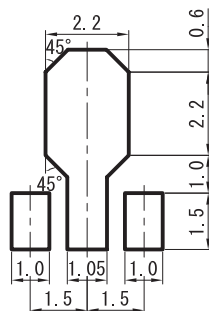


MiniP3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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